

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Previously Presented) A method for manufacturing an electro-optical substrate including a composite base plate obtained by joining a support plate to a semiconductor plate having semiconductor layers, comprising:
  - forming a light-shielding layer, having a predetermined pattern, over a support plate;
  - forming an insulating layer over the light-shielding layer having the predetermined pattern;
  - providing a semiconductor layer over the insulating layer;
  - partially oxidizing the semiconductor layer to form an oxide layer; and
  - completely removing the oxide layer, the oxide layer having a thickness smaller than that of the insulating layer.
2. (Previously Presented) The method for manufacturing an electro-optical substrate according to Claim 1, further comprising:
  - patterning the semiconductor layer; and
  - oxidizing parts of the semiconductor layer having a predetermined pattern to form the oxide layer,
  - the patterning step and oxidizing step being performed after the semiconductor layer-providing step.
3. (Canceled)
4. (Previously Presented) The method for manufacturing an electro-optical substrate according to Claim 1, the oxide layer having a thickness smaller than that of parts of

the insulating layer disposed in areas above which the semiconductor layer is not placed, and which are disposed on the light-shielding layer.

5. (Original) The method for manufacturing an electro-optical substrate according to Claim 1, further comprising:

forming a silicon nitride layer or silicon oxide nitride layer between the light-shielding layer and the insulating layer.

6. (Previously Presented) The method for manufacturing an electro-optical substrate according to Claim 1, the semiconductor layer-providing step including a sub-step of joining a single-crystal semiconductor plate including the semiconductor layer to a support plate including the insulating layer.

7. (Original) The method for manufacturing an electro-optical substrate according to Claim 1, the light-shielding layer containing a high-melting metal or a silicide containing a high-melting metal.

8. (Original) A method for manufacturing an electro-optical apparatus including a semiconductor element, comprising manufacturing an electro-optical substrate including the semiconductor element by the manufacturing method according to Claim 1.

9. Cancelled.